



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-11-14
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7BUI*068FCL2	A	LGGA	2014-11-14
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,16.25,4,5	3	Through-hole	
Comment	UI TO 220 ISOL FULL PACK 0.5 AB; MD valid for CP:T610T-8FP.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices

QueryList : REACH-16th June 2014			
Query			Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH			true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application
			ppm in product

Material Composition Declaration						Mfr Item Name	7BUI*068FCL2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.31	mg	supplier	die	Silicon (Si)	7440-21-3		2.868	mg	866465	1509
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.167	mg	50453	88
die (s)				supplier	passivation	Alumina	1344-28-1		0.023	mg	6949	12
die (s)				JIG - R	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and	0.21	mg	63444	111
die (s)				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.014	mg	4230	7
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1511	3
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6949	12
Leadframe	Copper & its alloys	611.212	mg	supplier	alloy	Copper (Cu)	7440-50-8		601.558	mg	984205	316609
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.277	mg	453	146
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.506	mg	828	266
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		8.816	mg	14424	4640
Leadframe				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	90	29
Soft solder	Solder	1.701	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.59	mg	934744	837
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.026	mg	15285	14
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.085	mg	49971	45
Bonding wire	Other inorganic materials	1.359	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.359	mg	1000000	715
encapsulation	Other Organic Materials	1276.552	mg	supplier	mold compound	Silica, vitreous	7631-86-9		929.33	mg	728000	489121
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		268.076	mg	210000	141093
encapsulation				supplier	mold compound	Phenolic resin	9003-35-4		63.827	mg	50000	33593
encapsulation				supplier	mold compound	Carbon black	1333-86-4		6.383	mg	5000	3359
encapsulation				supplier	mold compound	Zinc borate	138265-88-0		8.936	mg	7000	4703
connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087